

# Research of Copper Thermal Spray Coating for Mitigating Electron Cloud



Custom Designed Vacuum Equipment for PFD and Semiconductor Manufacturing  
Komiyama Electron Co., Ltd.

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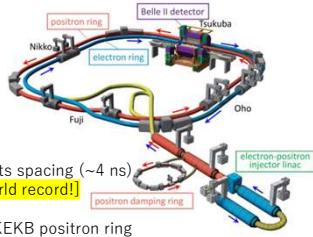
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## Introduction

**SuperKEKB**  $e^- - e^+$  two-ring collider consisting of

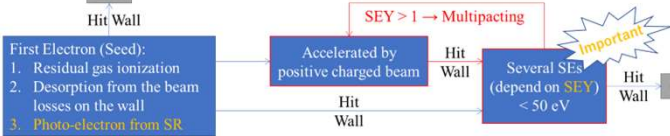
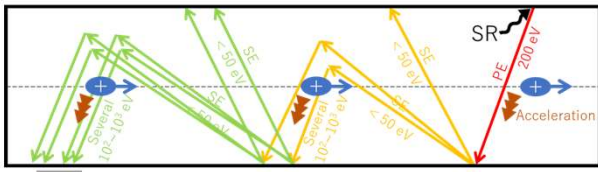
- BELLE-II detector
- Injector (Linac): L ~600 m
- Damping ring (e<sup>+</sup>): C ~135 m
- Main ring (MR): C ~3016 m
- HER: 7 GeV/e<sup>+</sup>, Max. current 1.14 A
- LER: 4 GeV/e<sup>-</sup>, Max. current 1.45 A



- Max. number of bunches = 2346 with ~2 RF-buckets spacing (~4 ns)
- Achieved peak luminosity:  $4.65 \times 10^{34} \text{ cm}^{-2}\text{s}^{-1}$  [World record!] (HER 1.10 A/LER 1.32 A/ 2249 bunches)
- The ECE will become a potential problem in SuperKEKB positron ring when we strive for a higher luminosity by increasing beam current in the future.

## Electron Cloud Effect (ECE)

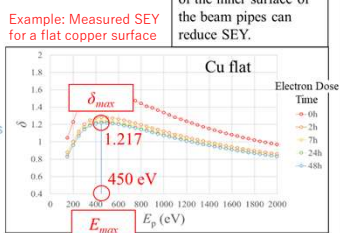
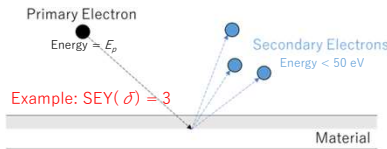
- For the beam with positive charge (proton and positron), the high-density electrons around the beam, also called as "electron cloud (EC)", cause the beam instability.
- Electron Cloud Formation:



- Beam size starts to increase at a threshold bunch current, resulting in the reduction of the luminosity.
- This is known as the electron cloud effect (ECE).
- Threshold electron density in SuperKEKB LER:  $3 \times 10^{11} / \text{m}^3$

## SEY

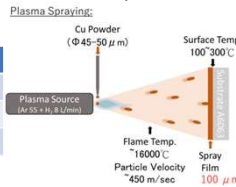
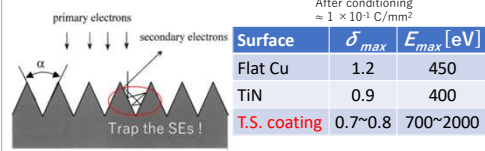
The Secondary Electron Yield (SEY or  $\delta$ ) is a primary parameter for controlling the ECE.



Conditioning: Electron bombardment of the inner surface of the beam pipes can reduce SEY.

## Thermal Spray

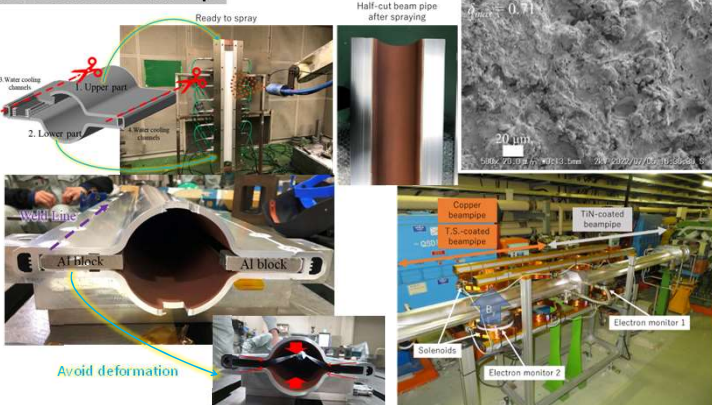
- Materials with Low SEY can be used to reduce ECE. TiN, for example, has been used in 90% of the SuperKEKB LER.
- In addition, rough surface generally has a lower SEY than smooth surface. However, a rough surface will increase the surface impedance, which may cause beam instability and increase heat load.



## Thermal Spray Coating (T.S. Coating)

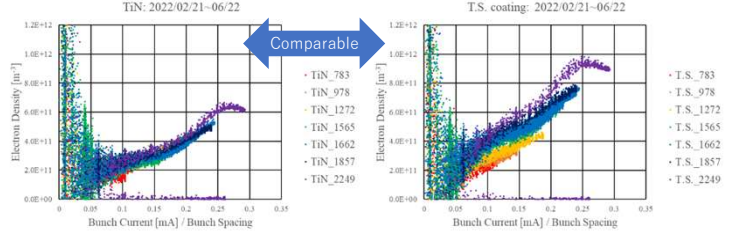
- Coating process: Melted or heated powdered materials are sprayed onto a surface.
- Original function: Protective layer, such as crankshaft reconditioning, corrosion protection, etc.
- Here we use this technology to increase roughness and, as a result, to reduce SEY.

## T.S.-Coated Beam Pipe



## Results

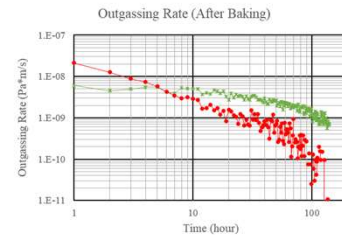
### Electron Density around the Beam



- These figures show the electron density around the beam against the current linear density (i.e., bunch current/ RF bucket spacing) in the TiN-coated and T.S.-coated beam pipes of SuperKEKB.
- The numbers on the right represent the bunch number.
- The electron density in the T.S.-coated beam pipe was in the same order as that of TiN-coated beam pipe.
- Another phenomenon to be aware of was that the electron density in the T.S.-coated beam pipe increased with the bunch number.
- It may be caused by the differences in the characteristics or locations between monitors (to be checked).

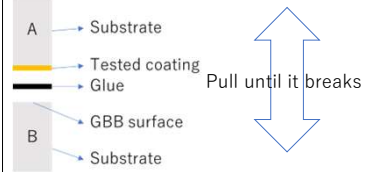
### Feasibility in Accelerators

#### Outgassing Rate Measurement



- Method: CM method
- Outgassing rates: T.S. coating ≈ Flat Al surface ( $< 1 \times 10^{-9} \text{ Pa}\cdot\text{m}^3/\text{s}$  after 100 h)
- Static desorption rate requirement of SuperKEKB:  $< 10^{-8} \text{ Pa}\cdot\text{m}^3/\text{s}$

#### Adhesive Strength



- Method: JIS H 8402
- $T = P/A$   
T [N/mm<sup>2</sup>]: Tensile adhesive strength  
P [N]: Tensile breaking load  
A [mm<sup>2</sup>]: Coating area
- T values [MPa]:  
- T.S. coating on Al: 29.17  
- Electroplating Cu on SS: 27.17

### Surface Resistance

Sample	$\sigma @ 5.044\text{GHz}$ [S/m]	$R_s = \sqrt{\frac{\pi \omega \mu_0}{\sigma}}$ [Ω]
Polished Cu	5.9E+7	1.8E-2
Machined Al	3.3E+7	2.5E-2
GBB Al	6.8E+6	5.4E-2
T.S. coating	1.9E+6	1.0E-1
Ti	2.4E+6	9.2E-2
SUS304	1.5E+6	1.2E-1

- Method: Cavity-resonator method
- Surface Resistance: T.S. coating ≈ Ti and SUS304

### Dust

- Method:



- Number of particles/coating area: T.S. coating ≈ NEG strip 707

## Conclusion

- The T.S. coating had a lower  $\delta_{max} = 0.7 \sim 0.8$  at higher  $E_{max}$  than that of flat Cu and TiN.
- The outgassing rate and adhesive strength of T.S. coating were adaptable.
- The amount of dust and impedance were not inconsiderable.
- The electron density in the T.S.-coated beam pipe installed in SuperKEKB LER was comparable to that of the TiN-coated beam pipes.
- In conclusion, according to the comprehensive evaluation, the T.S. coating can be considered as a candidate technology for reducing ECE, while there are still room for improvement.
- This study can provide a new and useful information for researchers in this field in developing a low-SEY coating on beam pipes.

